

IN THE CLAIMS:

Please amend Claims 1, 4, 7 and 11 as follows. A marked-up copy of Claims 1, 4, 7 and 11 showing the changes made thereto, is attached.

Sub E17
D1

1. (Twice Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging like a plane a plurality of substrates on each of which thin film semiconductor elements which are two-dimensionally arranged are installed comprising:

cutting a substrate having a slice line provided on the substrate and a guide line provided, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line.

Sub E27
D2

4. (Twice Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging like a plane a plurality of substrates on each of which thin film semiconductor elements which are two-dimensionally arranged are installed comprising:

D2
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cutting a substrate having a slice line provided on the substrate and a guide line provided, which corresponds to the slice line and is different from the slice line; and

detecting a position of the guide line and correcting a cutting position while the substrate is cut along the slice line, wherein the guide line is an electrode line provided on the substrate.

Sub E37
D3

7. (Twice Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device constructed by adjacently arranging like a plane a plurality of substrates on each of which thin film semiconductor elements which are two-dimensionally arranged are installed comprising:

cutting a substrate having an electrode layer provided on the substrate;

detecting, during the cutting, a position of a guide line provided corresponding to a slice line formed by the electrode layer; and

correcting a cutting position based on the detection in said detecting step.

Sub E47
D4

11. (Twice Amended) A substrate cutting method for cutting a substrate of a thin film semiconductor device